



MDSA Series

SMD Low Profile High Current Molded Inductor

Size 1360



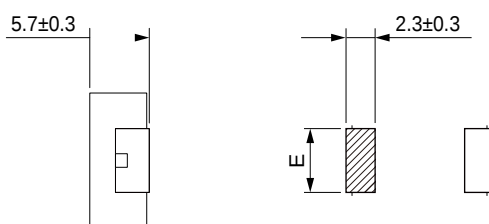
FEATURES

- Shielded construction
- Capable of corresponding high frequency
- Low loss realized with low DCR
- High performance (Isat) realized by metal dust core
- Ultra low buzz noise, due to composite construction
- 100% Lead(Pb)-Free and RoHS compliant
- AEC-Q200 qualified
- Operating temperature: -55 to +155 °C(including self-temperature rise)
- Quantity: 500PCS

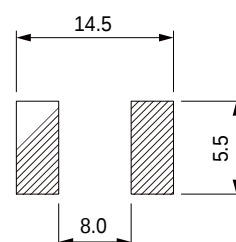
APPLICATION

- Noise filter for various drive circuitry requiring high temp. operation and peak current handling capability
- Boost-Converter
- Buck-Converter DC/DC

Dimensions: [mm]



Land Pattern: [mm]



Electrical Properties:

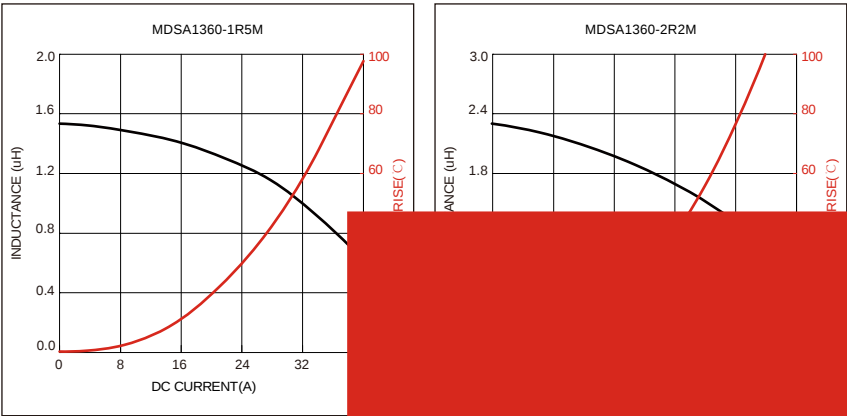
Part No	Inductance @ 100KHz/1V	Tolerance	Temperature Rise Current Typ. (A)	Current Typ. (A)	DC Resistance Typ.	DC Resistance Max.	E
MDSA1360-1R5M		±20%	27.0	31.0	3.00	3.50	4.0±0.3
MDSA1360-2R2M		±20%	24.0	27.0	4.00	4.70	4.7±0.3
MDSA1360-3R3M	3.30	±20%	20.0	27.0	5.70	7.00	4.7±0.3
MDSA1360-4R7M	4.70	±20%	18.0	22.0	7.80	9.20	4.7±0.3
MDSA1360-8R2M	8.20	±20%	13.0	16.0	14.0	17.0	4.7±0.3
MDSA1360-100M	10.0	±20%	11.5	15.5	16.8	20.0	4.7±0.3
MDSA1360-150M	15.0	±20%	9.5	9.5	25.0	30.0	4.7±0.3
MDSA1360-220M	22.0	±20%	7.8	8.8	32.0	38.8	4.7±0.3
MDSA1360-330M	33.0	±20%	6.6	7.6	57.0	69.0	4.7±0.3
MDSA1360-470M	47.0	±20%	5.0	6.5	78.0	90.0	4.7±0.3

Saturation Current will cause L to drop approximately 30%

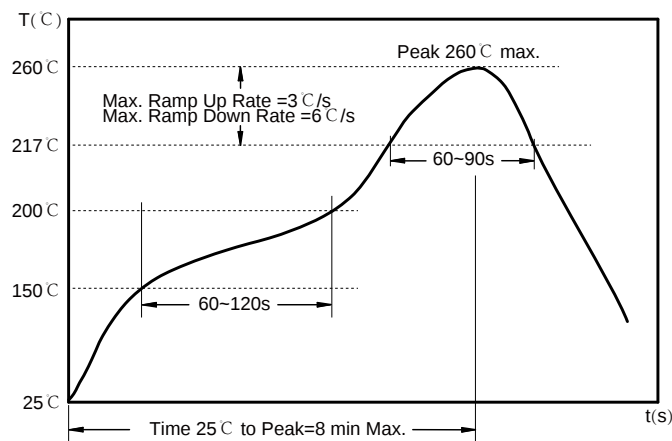
Temperature Rise Current: The actual value of DC current when the temperature rise is $\Delta T=40^{\circ}\text{C}$



Typical Electrical Characteristics:



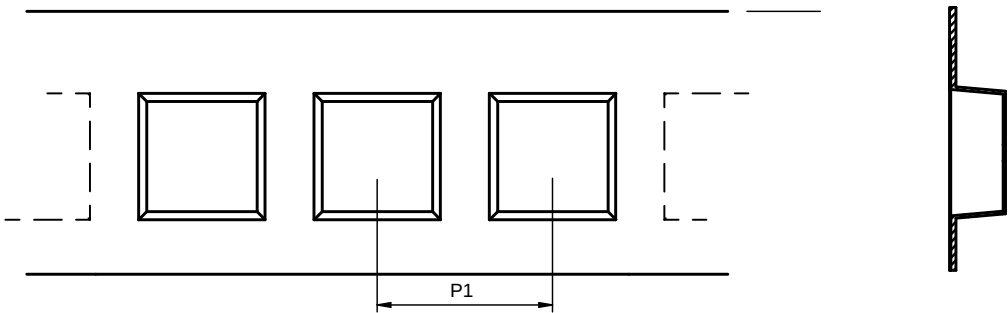
Soldering Reflow:



Preheat condition: 150 ~200 °C / 60~120 sec.
Allowed time above 217 °C : 60~90 sec.
Max temperature: 260 °C .
Max time at max temperature: 10 sec.
Allowed Reflow time: 2x max.

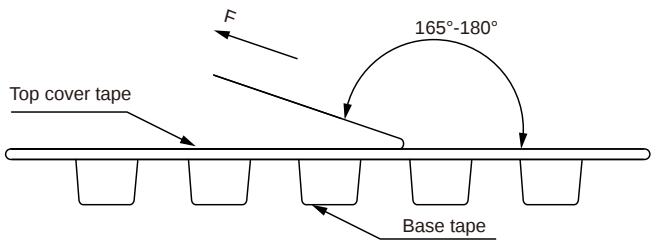
Packaging Information:

Tape Dimension :



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
KBQ?/14.	/1,/ ° .,/	/2,. ° .,/	/,3 ° .,/	2,. ° .,/	/4,. ° .,/	02,. ° .,1	4,1 ° .,/	/,53 ° .,/	.,3. ° .,.3

Peel force of top cover tape:



Rfc nccj dmpac md rmn amtcp r_nc qf_jj `c `crucc l .,/ rm /,1 L

Product Marking:

K_pigle	IF)Npglrgle Glbsar_lac'
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